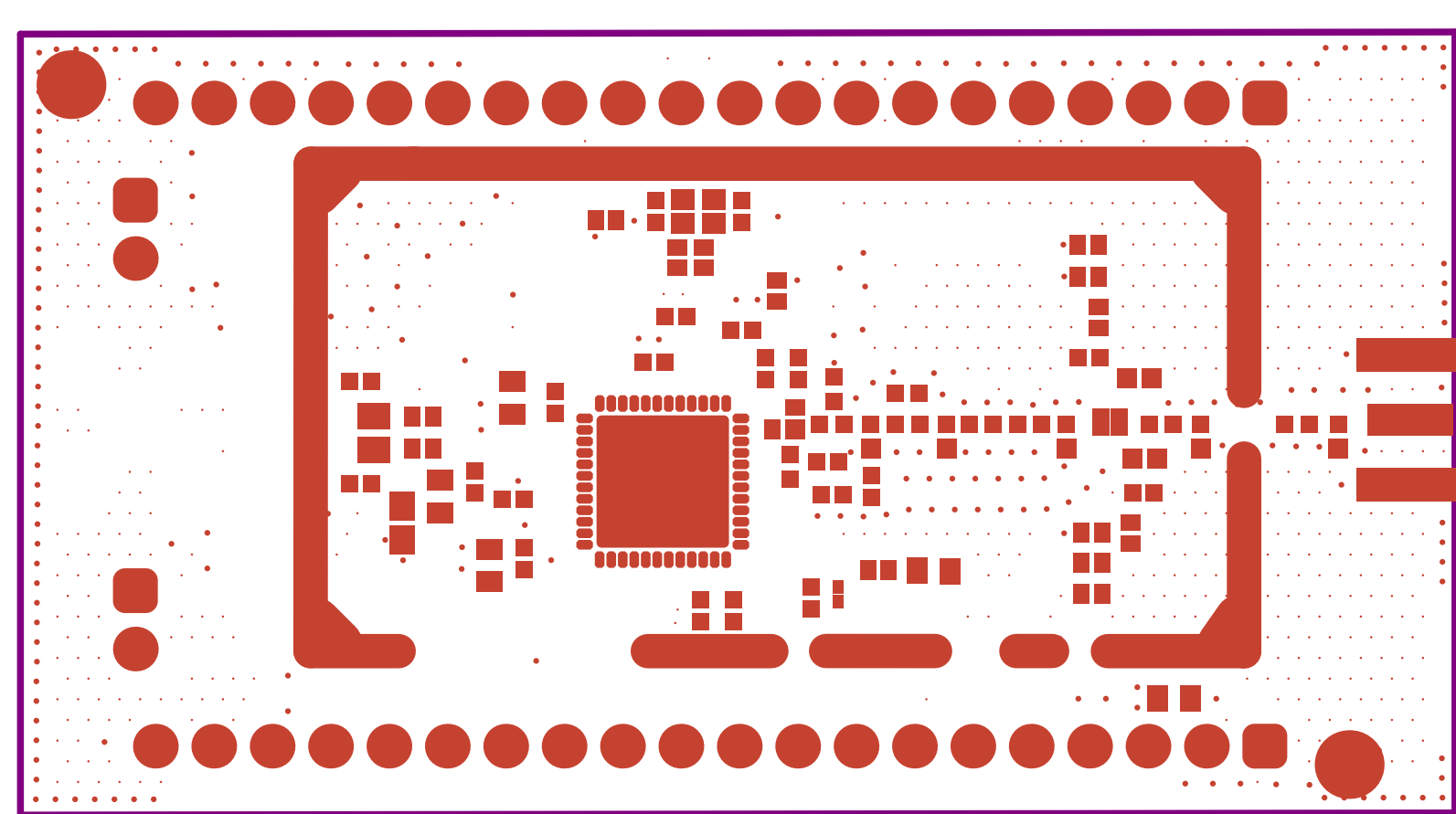
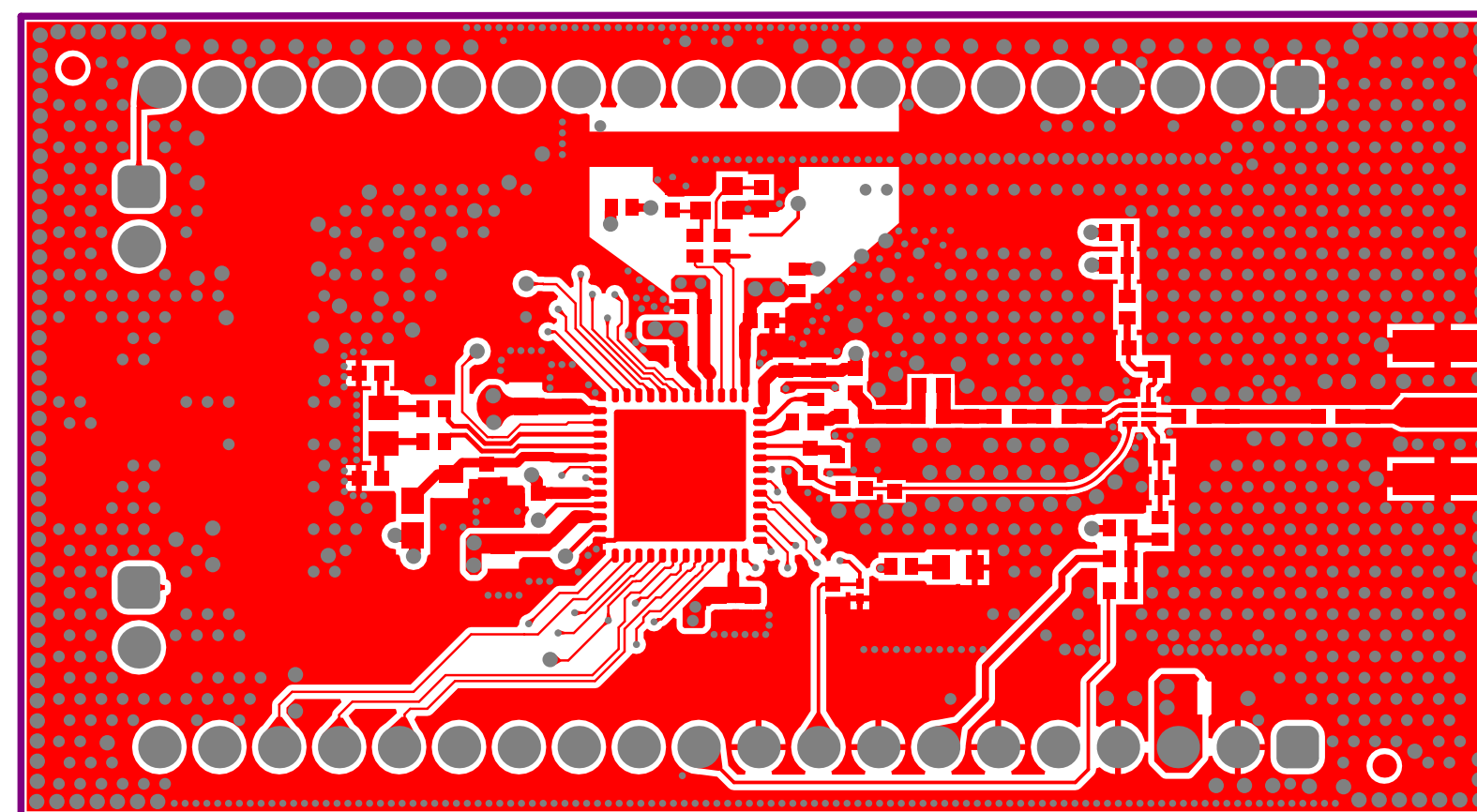


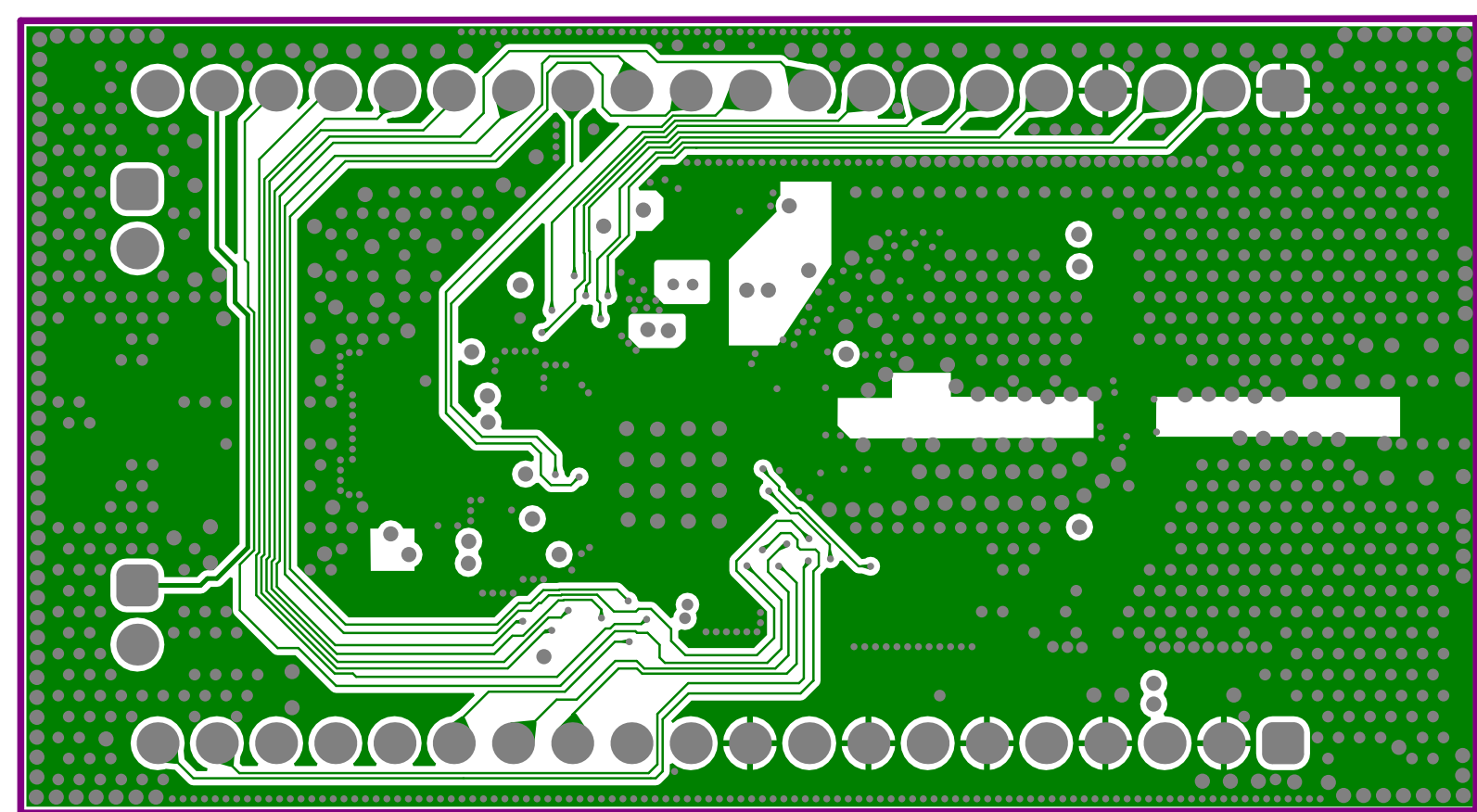


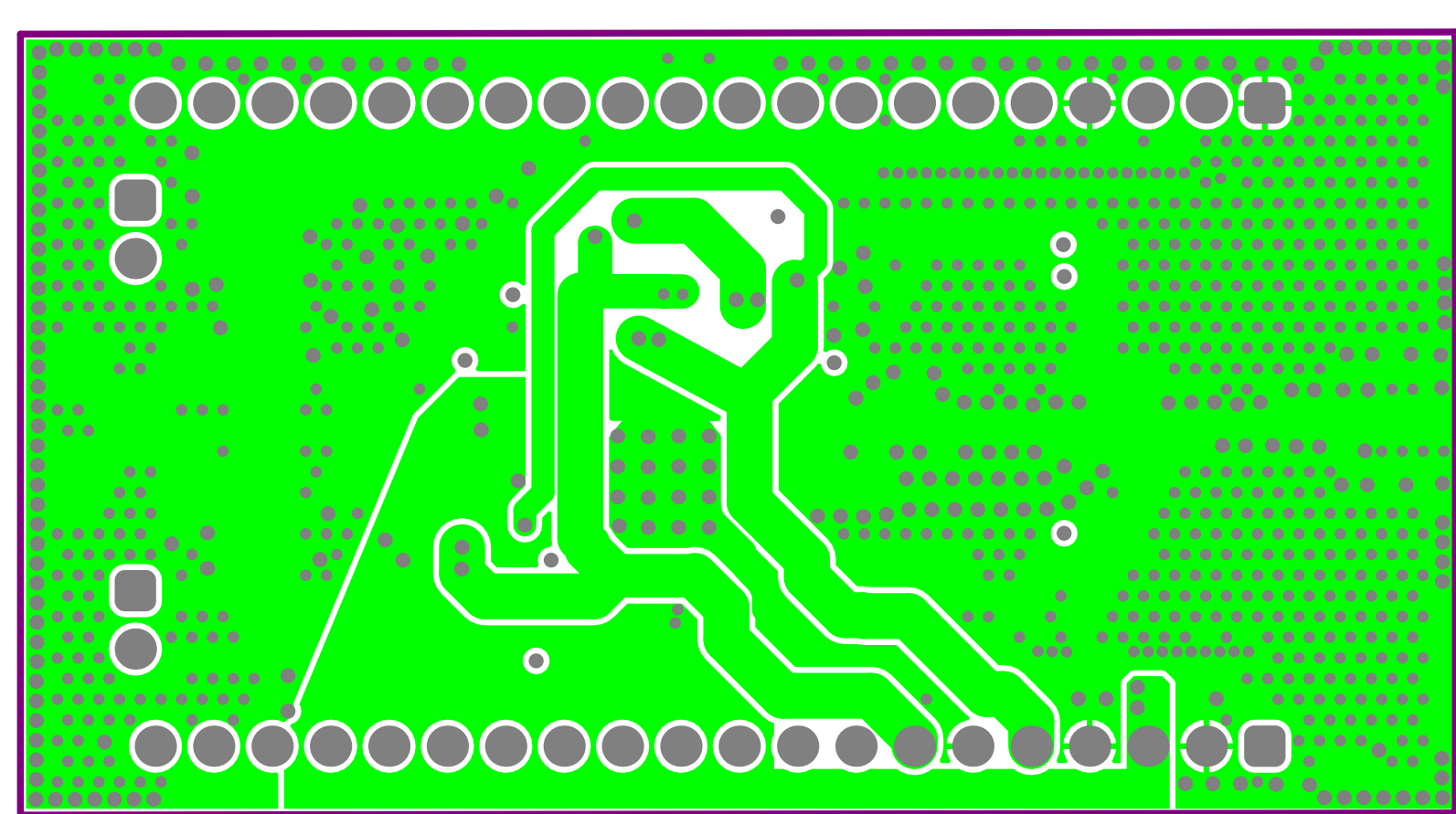
.GTO



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.79mil	3.5	
1	Top Layer		2.13mil		
	Dielectric 1	1 X 2116	4.25mil	3.6	
2	MidLayer 1		1.38mil		
	Dielectric 2	FR4 TG135	47.24mil	4.7	
3	MidLayer 2		1.38mil		
	Dielectric 3	1 X 2116	4.25mil	3.6	
4	Bottom Layer		2.13mil		
	Bottom Solder	Solder Resist	0.79mil	3.5	
	Bottom Overlay				

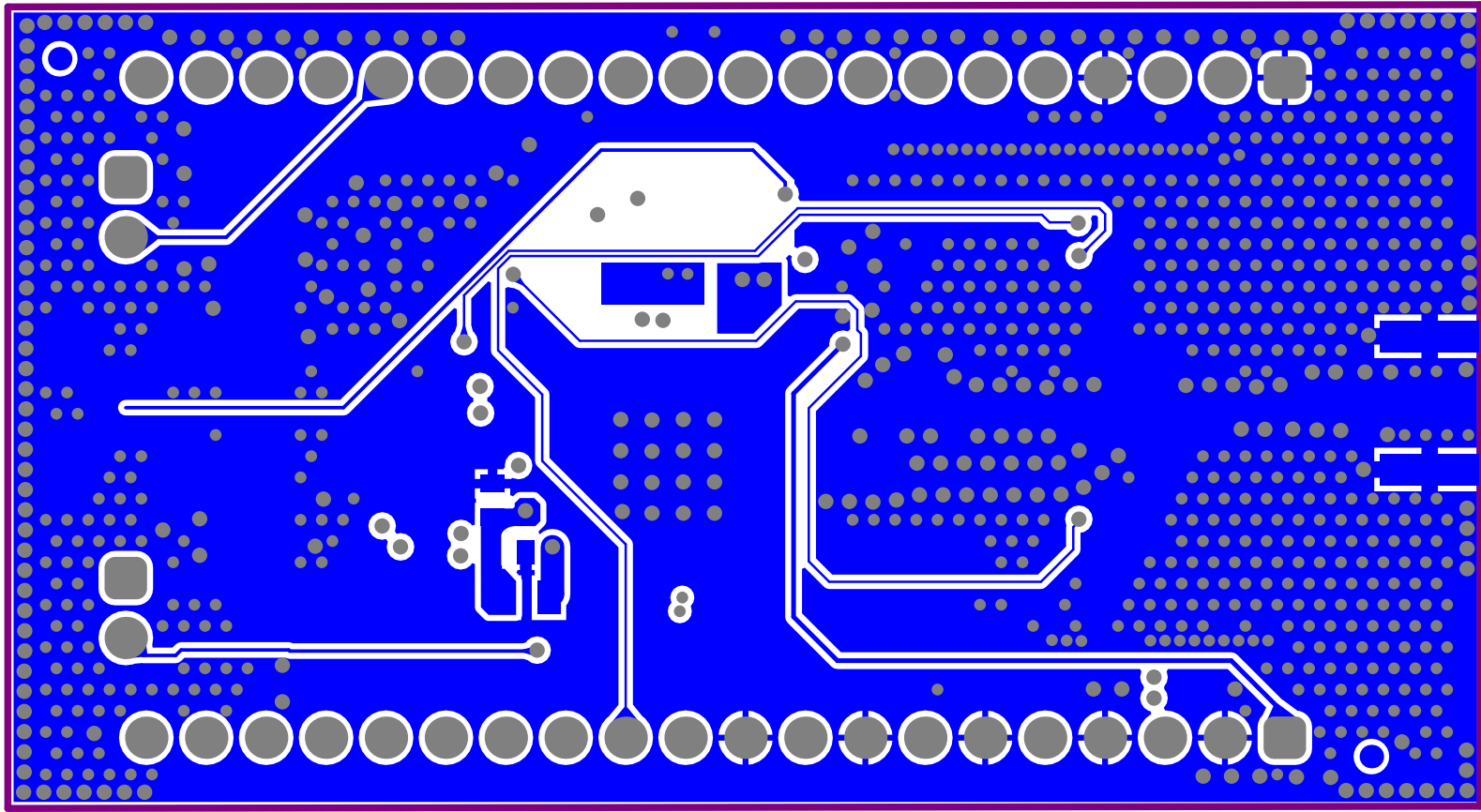


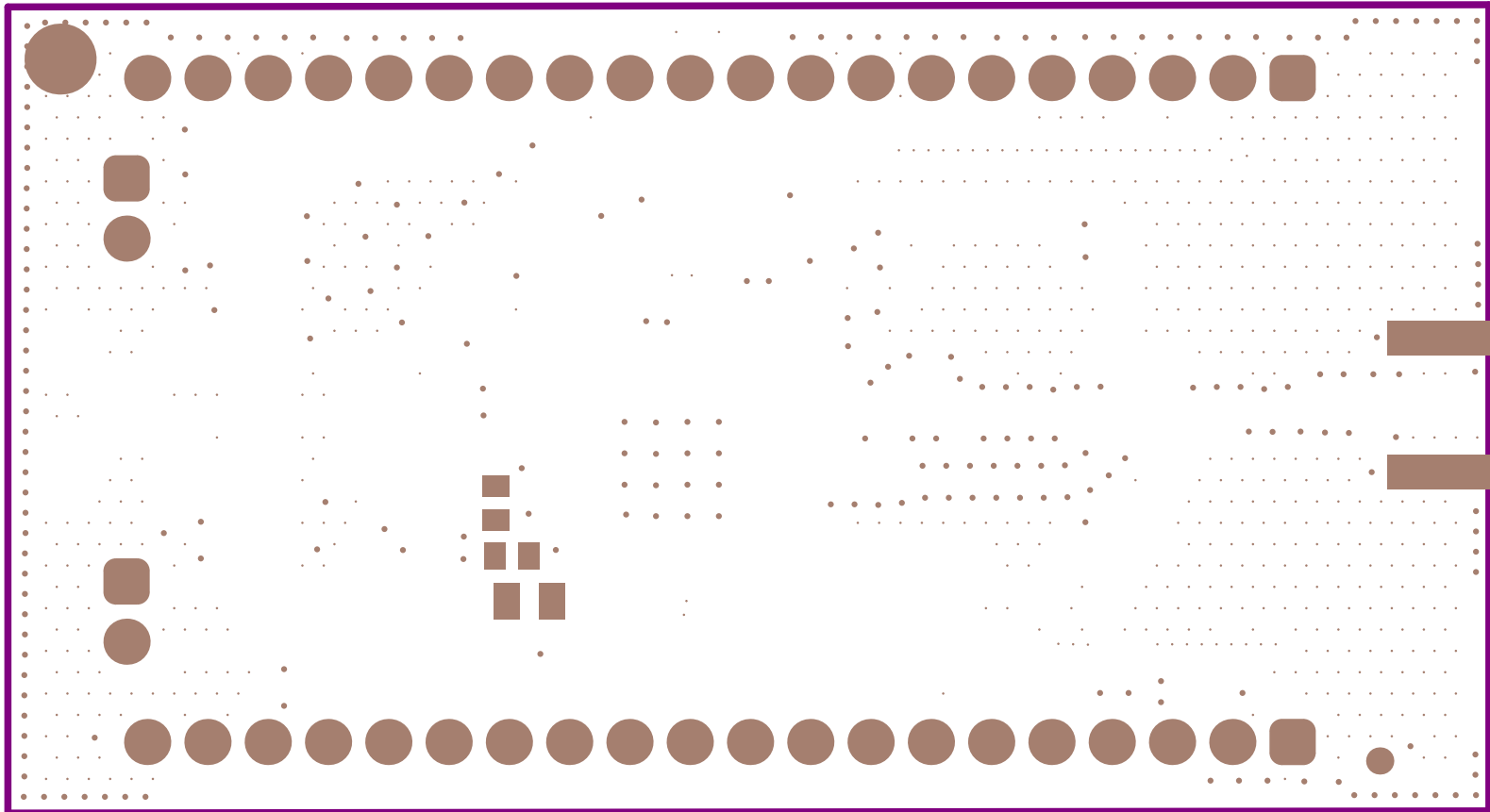


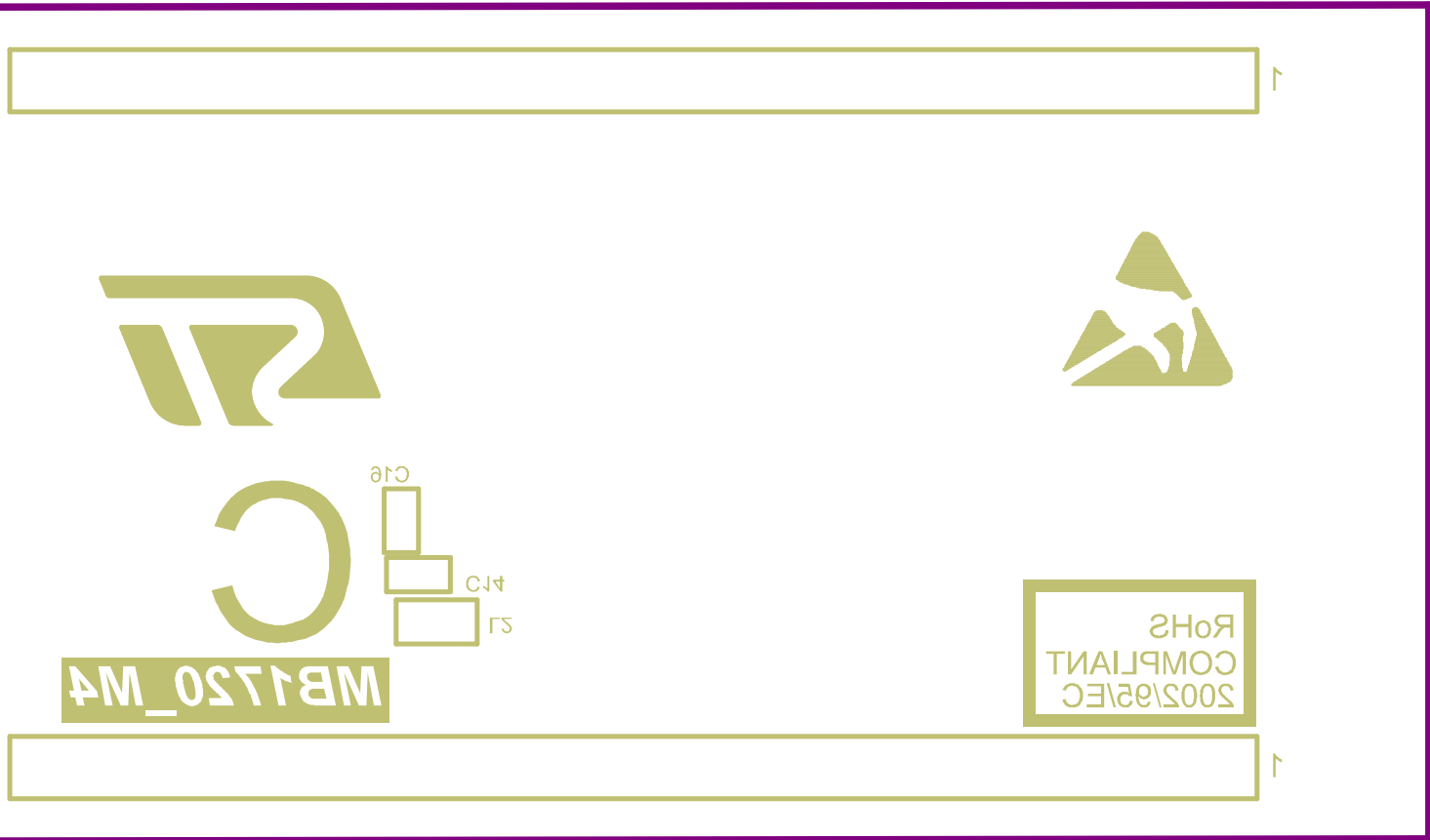


Bottom Layer

.GBL







Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair		Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)		Hole Tolerance (-)		Hole Length	Routed Path Length	
Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer	Plating Layer	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)		Hole Tolerance (-)		Hole Length	Routed Path Length	
⌀	928	0.226mm (7.82mil)	PPMH	Roadd	TopLayer	BottomLayer	Via	Rounded	v30mm2x					-	-	-	-
	986 Total																

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differential)	TOL.
TOP	23.62	7.28	50 ohm	NA	+/- 10%

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☒TG-170

☐TG-150

☐TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☒GREEN

☐BLUE

☐RED

☐BLACK

D. SILKSCREEN COLOR :

☒WHITE

☐YELLOW

☐BLACK

E. SURFACE FINISH :

☒ENIG

☐IMMERSION SILVER

☐IMMERSION TIN

☐HASL

☐HASL (PB-FREE)

☐GOLDEN FINGER

☐IMPEDANCE CONTROL :

☐NO

☒YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒SOLDERMASK

☐NON-CONDUCTIVE EPOXY.

☐STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

